



Click [here](#) for the 3D model.

### Dimensions

|           |                 |
|-----------|-----------------|
| Chip Size | 0402            |
| L         | 1mm +/-0.05mm   |
| W         | 0.5mm +/-0.05mm |
| T         | 0.5mm +/-0.05mm |
| B         | 0.25mm +/-0.1mm |

### Packaging Specifications

|                    |                          |
|--------------------|--------------------------|
| Packaging          | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 10000                    |

### General Information

|                |  |
|----------------|--|
| Series         | CBR-SMD RF Auto COG                            |
| Style          | SMD Chip                                       |
| Description    | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features       | Ultra High Q, Low ESR, Class I                 |
| RoHS           | Yes  |
| Termination    | Tin  |
| Marking        | No   |
| Qualifications | AEC-Q200                                       |
| AEC-Q200       | Yes  |
| Halogen Free   | Yes  |
| Notes          | Solder Wave or Solder Reflow.                  |
| Shelf Life     | 78 Weeks                                       |
| MSL            | 1  |

### Specifications

|  |                        |
|--|------------------------|
| Capacitance  | 16 pF                  |
| Capacitance Tolerance  | 5%                     |
| Voltage DC   | 50 VDC                 |
| Dielectric Withstanding Voltage                                    | 125 VDC                |
| Temperature Range  | -55/+125°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor   | 0.14% 1MHz 1.0Vrms     |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 10 GOhms               |
| Quality Factor   | 720                    |